



## Material Content Data Sheet



<b>Sales Product Name</b>		TLS208D1EJV33		<b>Issued</b>		9. June 2015		
<b>MA#</b>		MA001331470						
<b>Package</b>		PG-DSO-8-27		<b>Weight*</b>		84.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.453	1.73	1.73	17298	17298
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.728	0.87		8662	
wire	non noble metal	copper	7440-50-8	29.548	35.17	36.09	351712	360915
	noble metal	gold	7440-57-5	0.253	0.30	0.30	3013	3013
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1190
plastics	plastics	epoxy resin	-	4.598	5.47		54734	
	inorganic material	silicondioxide	60676-86-0	45.283	53.91	59.50	539013	594937
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8274	8274
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8624	8624
glue	plastics	epoxy resin	-	0.146	0.17		1735	
	noble metal	silver	7440-22-4	0.437	0.52	0.69	5204	6939
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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